

NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.

Contact: Copper Alloy

Shell: STAINLESS

PLATING:

Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F

Shell: Plated 30u" Ni Overall

Plated G/F Selective Contact Area

Electrical:

Current Rating :0.5mA max.

Voltage Rating :50V DC MAX

Ambient Temperature Range :-20°C~+85°C

Storage Temperature Range :-40°C~+70°C

Ambient Humidity Range :95% R.H. Max.

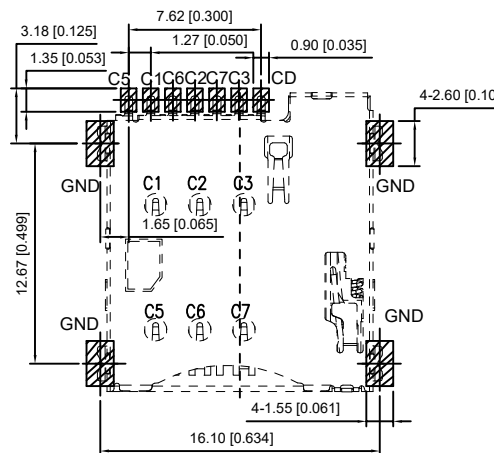
Contact Resistance:100mΩmax.

Insulation Resistance:1000MΩ min./250V DC

Dielectric Withstanding Voltage:500V AC

Mating Cycles:5,000 Insertions

Temperature: 260°C ±5°



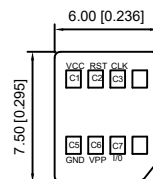
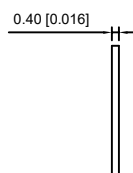
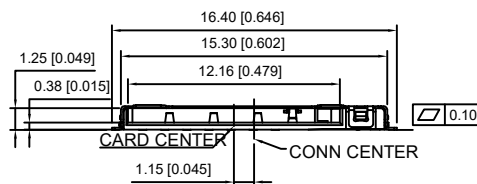
SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

■ SMT SOLDER AREA

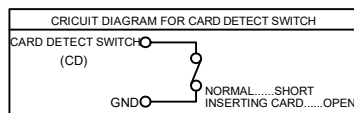
THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ±0.05



MICRO SIM CARD



ECN BO.		DESCRIPTION.		DATE.	REV.	SCALE: 3:1	
DESIGNED	CHECKED	APPROVAL	DRAWING NUMBER		SCALT: 1/2	SCALE: 3:1	
Mikey	Tom	Jerry	PART NAME	SIM-002-P7	UNLESS OTHERWISE SPECIFIED, TOLERANCE:	X.	±0.25
			MODEL NAME	SIM-002-P7		X.x	±0.20
			3RD ANGLE PROJ	HanElectricity Co.,LTD		X.xx	±0.15
						ANGULAIR	±3
						FILE.NO.	

瀚源